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(71) Applicant: **MATSUSHITA ELECTRIC IND CO LTD**

(72) Inventor: **SHINPO TOSHIHARU
TSUYAMA KAZUHIKO
MIKI TOSHINOBU**

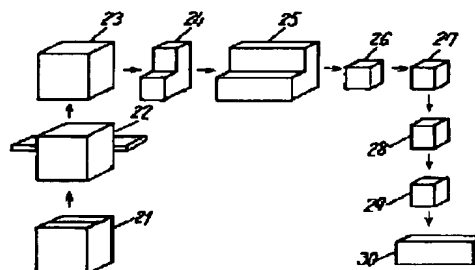
(54) **METHOD AND DEVICE FOR MANUFACTURING
ELECTRONIC UNIT**

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(57) Abstract:

PROBLEM TO BE SOLVED: To reduce correction work related to the manufacture of electronic units with a reflow solder by protecting non-heat-resistant parts from high temperature and performing good soldering.

SOLUTION: A cream solder printer 21, wherein a cream solder is printed on the one surface of a printed board, a chip-attaching machine 22 wherein a surface-mounting part is attached on the printed board where the cream solder is printed, a first reflow oven 23 where the surface-mounting part is bonded to the printed board, a solder-applying machine 24 with which a cream solder or attachment of a profile part on the printed board is applied, and a second reflow oven 30 wherein, after the profile part has been inserted in the printed board, the profile part is bonded to the printed board, are provided. Here, for the second reflow oven 30, the temperature at the other surface of the printed board is set lower than that at the one surface.



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